MPSW45, MPSW45A

One Watt Darlington Transistors

NPN Silicon

Features

- Pb−Free Packages are Available*

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Collector − Emitter Voltage	MPSW45 MPSW45A	V_{CES}	40 50	Vdc
Collector − Base Voltage	MPSW45 MPSW45A	V_{CBO}	50 60	Vdc
Emitter − Base Voltage		V_{EBO}	12	Vdc
Collector Current − Continuous		I_C	1.0	Adc
Total Device Dissipation @ T_A = 25°C Derate above 25°C		P_D	1.0 8.0	W mW/°C
Total Device Dissipation @ T_C = 25°C Derate above 25°C		P_D	2.5 20	W mW/°C
Operating and Storage Junction Temperature Range		T_J, T_{stg}	−55 to +150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	125	°C/W
Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	50	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

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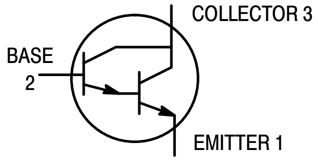
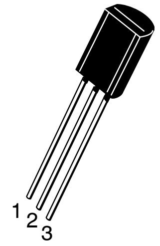
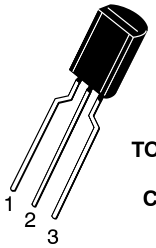




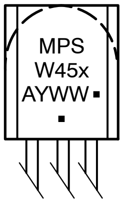
STRAIGHT LEAD
BULK PACK



BENT LEAD
TAPE & REEL
AMMO PACK

TO−92 1 WATT
(TO−226)
CASE 29−10
STYLE 1

MARKING DIAGRAM



MPSW45x = Device Code
x = 45A Devices
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

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*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

August, 2010 − Rev. 4

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage (I_C = 100 μAdc, V_{BE} = 0)	MPSW45 MPSW45A	$V_{(BR)CES}$	40 50	– –	Vdc
Collector–Base Breakdown Voltage (I_C = 100 μAdc, I_E = 0)	MPSW45 MPSW45A	$V_{(BR)CBO}$	50 60	– –	Vdc
Emitter–Base Breakdown Voltage (I_E = 10 μAdc, I_C = 0)		$V_{(BR)EBO}$	12	–	Vdc
Collector Cutoff Current (V_{CB} = 30 Vdc, I_E = 0) (V_{CB} = 40 Vdc, I_E = 0)	MPSW45 MPSW45A	I_{CBO}	– –	100 100	nAdc
Emitter Cutoff Current (V_{EB} = 10 Vdc, I_C = 0)		I_{EBO}	–	100	nAdc
ON CHARACTERISTICS (Note 1)					
DC Current Gain (I_C = 200 mAdc, V_{CE} = 5.0 Vdc) (I_C = 500 mAdc, V_{CE} = 5.0 Vdc) (I_C = 1.0 Adc, V_{CE} = 5.0 Vdc)		h_{FE}	25,000 15,000 4,000	150,000 – –	–
Collector–Emitter Saturation Voltage (I_C = 1.0 Adc, I_B = 2.0 mAdc)		$V_{CE(sat)}$	–	1.5	Vdc
Base–Emitter Saturation Voltage (I_C = 1.0 Adc, I_B = 2.0 mAdc)		$V_{BE(sat)}$	–	2.0	Vdc
Base–Emitter On Voltage (I_C = 1.0 Adc, V_{CE} = 5.0 Vdc)		$V_{BE(on)}$	–	2.0	Vdc
SMALL–SIGNAL CHARACTERISTICS					
Current–Gain – Bandwidth Product (I_C = 200 mAdc, V_{CE} = 5.0 Vdc, f = 100 MHz)		f_T	100	–	MHz
Collector–Base Capacitance (V_{CB} = 10 Vdc, I_E = 0, f = 1.0 MHz)		C_{cb}	–	6.0	pF

1. Pulse Test: Pulse Width ≤ 300 μs; Duty Cycle ≤ 2.0%.

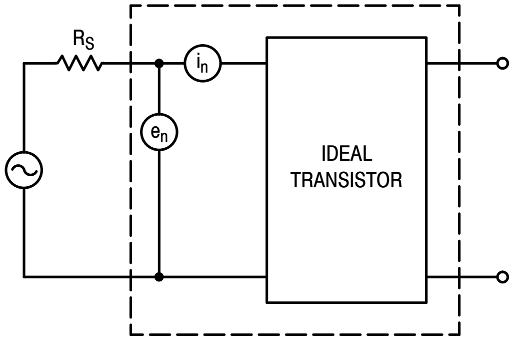


Figure 1. Transistor Noise Model

NOISE CHARACTERISTICS

(V_{CE} = 5.0 Vdc, T_A = 25°C)

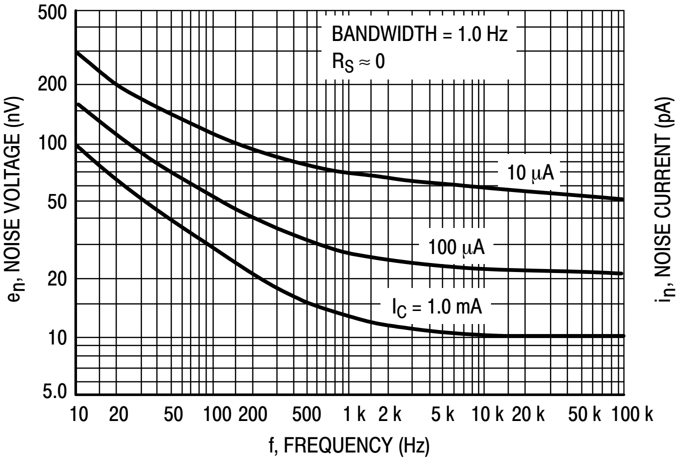


Figure 2. Noise Voltage

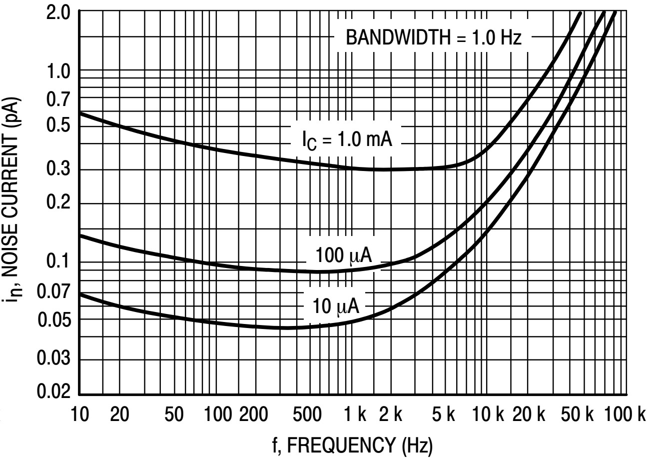


Figure 3. Noise Current

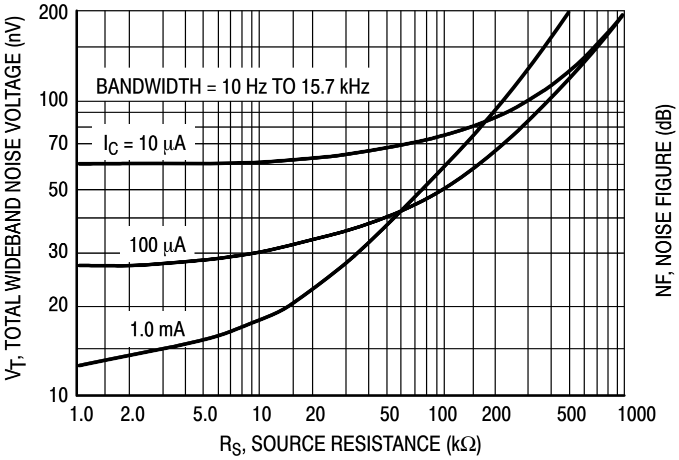


Figure 4. Total Wideband Noise Voltage

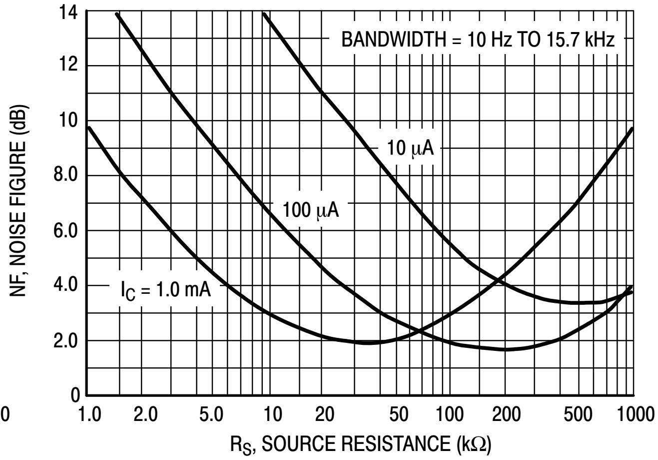


Figure 5. Wideband Noise Figure

SMALL−SIGNAL CHARACTERISTICS

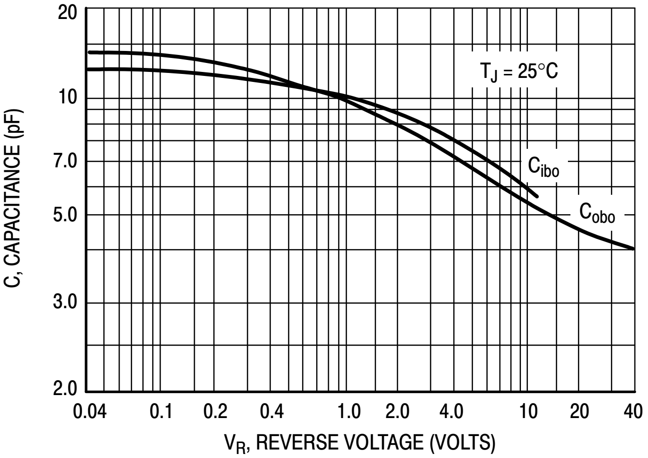


Figure 6. Capacitance

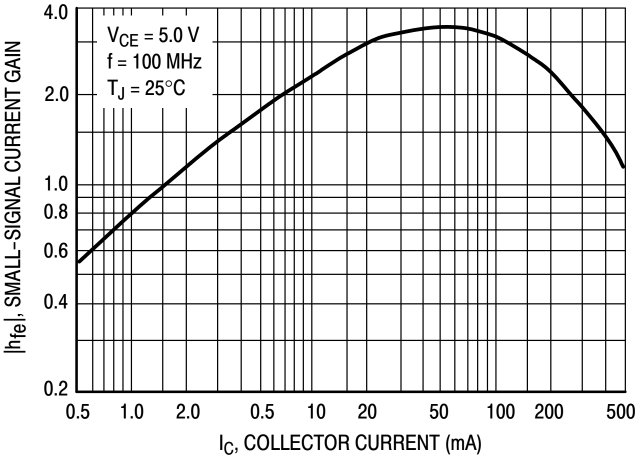


Figure 7. High Frequency Current Gain

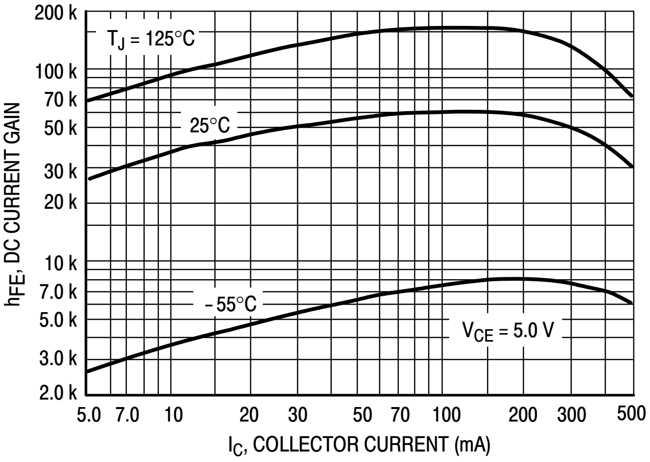


Figure 8. DC Current Gain

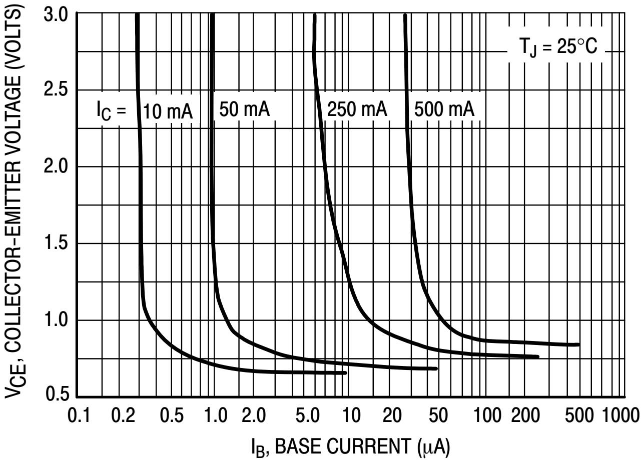


Figure 9. Collector Saturation Region

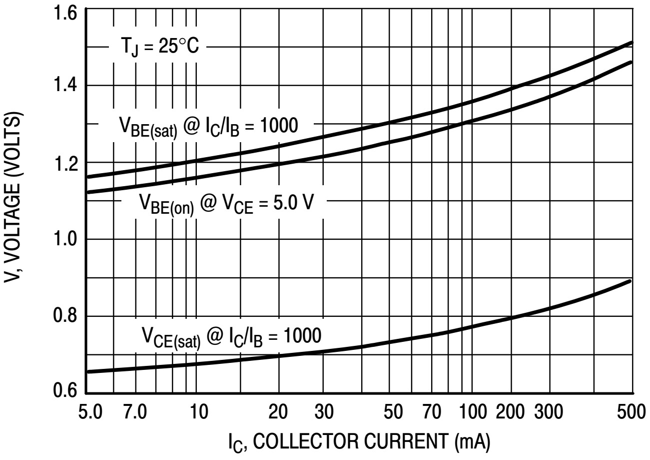


Figure 10. “On” Voltages

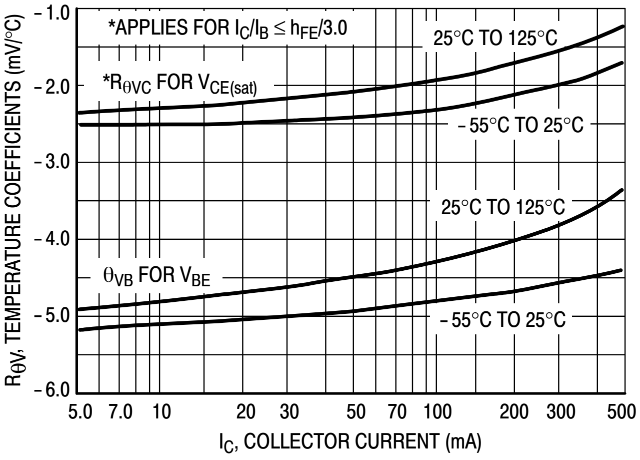


Figure 11. Temperature Coefficients

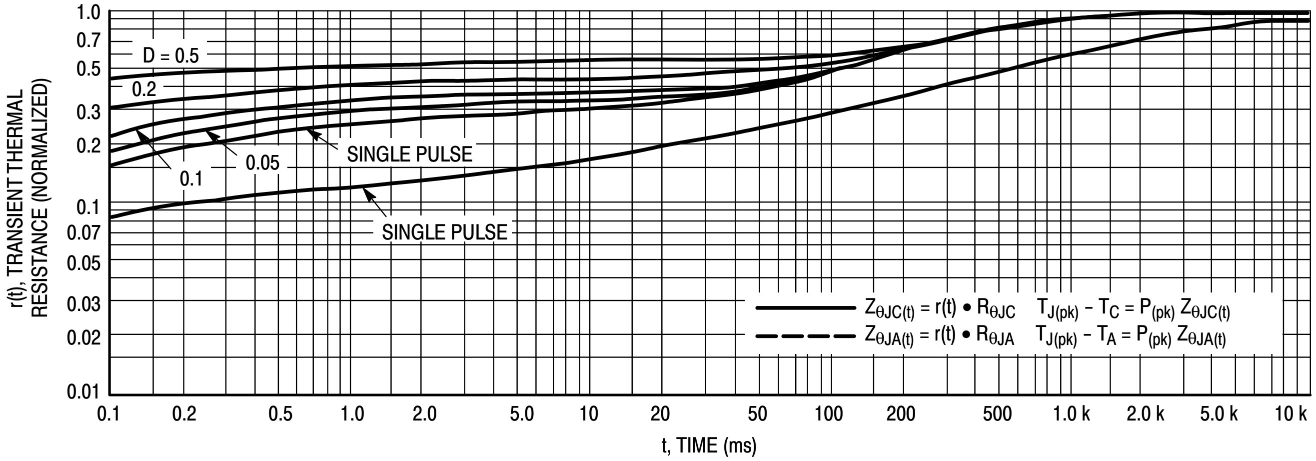


Figure 12. Thermal Response

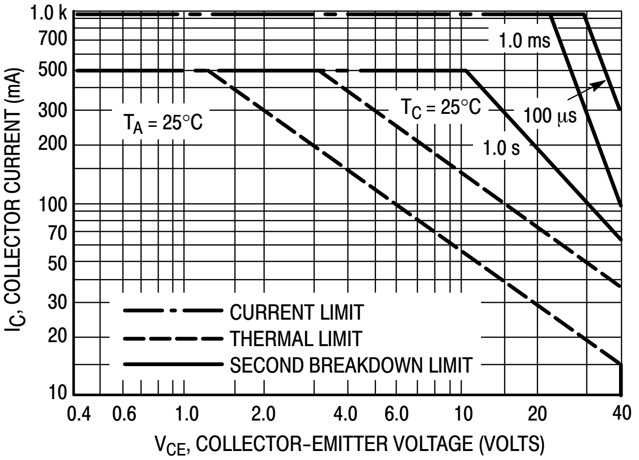
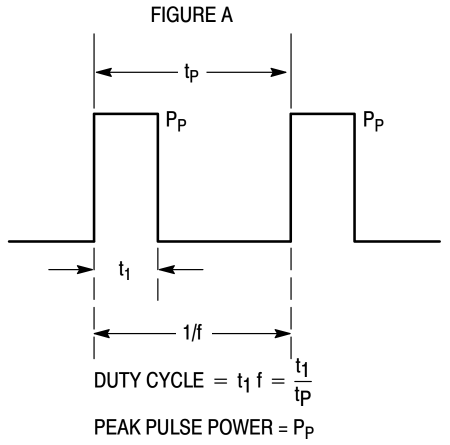


Figure 13. Active Region Safe Operating Area



Design Note: Use of Transient Thermal Resistance Data

ORDERING INFORMATION

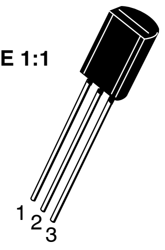
Device	Package	Shipping†
MPSW45G	TO−92 (Pb−Free)	5,000 Units / Box
MPSW45RLREG	TO−92 (Pb−Free)	2,000 / Tape & Reel
MPSW45A	TO−92	5,000 Units / Box
MPSW45AG	TO−92 (Pb−Free)	5,000 Units / Box
MPSW45ARLRA	TO−92	2,000 / Tape & Reel
MPSW45ARLRAG	TO−92 (Pb−Free)	2,000 / Tape & Reel
MPSW45AZL1	TO−92	2,000 / Ammo Pack
MPSW45AZL1G	TO−92 (Pb−Free)	2,000 / Ammo Pack

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

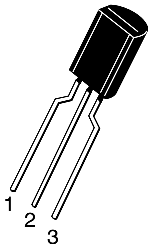
TO−92 (TO−226) 1 WATT
CASE 29−10
ISSUE D

DATE 05 MAR 2021

SCALE 1:1

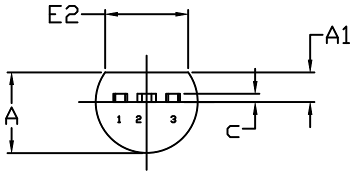


STRAIGHT LEAD

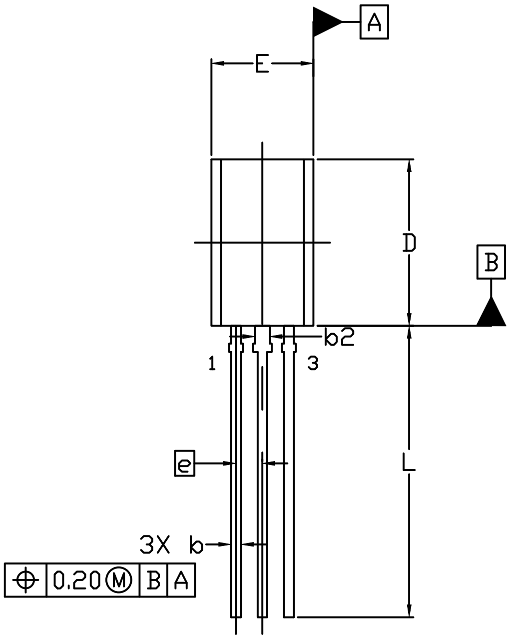


BENT LEAD

STRAIGHT LEAD



END VIEW



TOP VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS.
4. DIMENSION b AND b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 0.20. DIMENSION b2 LOCATED ABOVE THE DAMBAR PORTION OF MIDDLE LEAD.

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	3.75	3.90	4.05
A1	1.28	1.43	1.58
b	0.38	0.465	0.55
b2	0.62	0.70	0.78
c	0.35	0.40	0.45
D	7.85	8.00	8.15
E	4.75	4.90	5.05
E2	3.90	---	---
e	1.27 BSC		
L	13.80	14.00	14.20

STYLES AND MARKING ON PAGE 3

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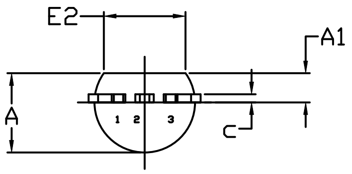
DESCRIPTION:	**TO−92 (TO−226) 1 WATT**	**PAGE 1 OF 3**

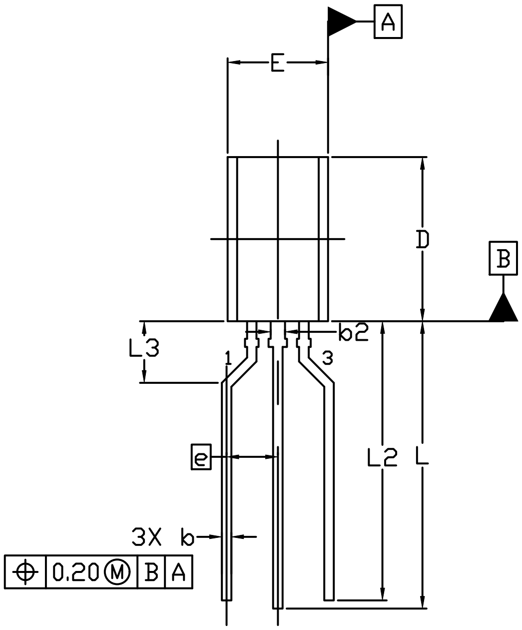
TO−92 (TO−226) 1 WATT
CASE 29−10
ISSUE D

DATE 05 MAR 2021

FORMED LEAD



END VIEW



TOP VIEW

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E2	3.90	---	---
e	2.50 BSC		
L	13.80	14.00	14.20
L2	13.20	13.60	14.00
L3	3.00 REF		

STYLES AND MARKING ON PAGE 3

TO−92 (TO−226) 1 WATT

CASE 29−10
ISSUE D

DATE 05 MAR 2021

STYLE 1:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 2:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 3:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 4:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 5:
PIN 1. DRAIN
2. SOURCE
3. GATE

STYLE 6:
PIN 1. GATE
2. SOURCE & SUBSTRATE
3. DRAIN

STYLE 7:
PIN 1. SOURCE
2. DRAIN
3. GATE

STYLE 8:
PIN 1. DRAIN
2. GATE
3. SOURCE & SUBSTRATE

STYLE 9:
PIN 1. BASE 1
2. EMITTER
3. BASE 2

STYLE 10:
PIN 1. CATHODE
2. GATE
3. ANODE

STYLE 11:
PIN 1. ANODE
2. CATHODE & ANODE
3. CATHODE

STYLE 12:
PIN 1. MAIN TERMINAL 1
2. GATE
3. MAIN TERMINAL 2

STYLE 13:
PIN 1. ANODE 1
2. GATE
3. CATHODE 2

STYLE 14:
PIN 1. EMITTER
2. COLLECTOR
3. BASE

STYLE 15:
PIN 1. ANODE 1
2. CATHODE
3. ANODE 2

STYLE 16:
PIN 1. ANODE
2. GATE
3. CATHODE

STYLE 17:
PIN 1. COLLECTOR
2. BASE
3. EMITTER

STYLE 18:
PIN 1. ANODE
2. CATHODE
3. NOT CONNECTED

STYLE 19:
PIN 1. GATE
2. ANODE
3. CATHODE

STYLE 20:
PIN 1. NOT CONNECTED
2. CATHODE
3. ANODE

STYLE 21:
PIN 1. COLLECTOR
2. EMITTER
3. BASE

STYLE 22:
PIN 1. SOURCE
2. GATE
3. DRAIN

STYLE 23:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 24:
PIN 1. EMITTER
2. COLLECTOR/ANODE
3. CATHODE

STYLE 25:
PIN 1. MT 1
2. GATE
3. MT 2

STYLE 26:
PIN 1. V_{CC}
2. GROUND 2
3. OUTPUT

STYLE 27:
PIN 1. MT
2. SUBSTRATE
3. MT

STYLE 28:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 29:
PIN 1. NOT CONNECTED
2. ANODE
3. CATHODE

STYLE 30:
PIN 1. DRAIN
2. GATE
3. SOURCE

STYLE 31:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 32:
PIN 1. BASE
2. COLLECTOR
3. EMITTER

STYLE 33:
PIN 1. RETURN
2. INPUT
3. OUTPUT

STYLE 34:
PIN 1. INPUT
2. GROUND
3. LOGIC

STYLE 35:
PIN 1. GATE
2. COLLECTOR
3. EMITTER

GENERIC MARKING DIAGRAM*

XXXXX
XXXXX
ALYW▪
▪

XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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